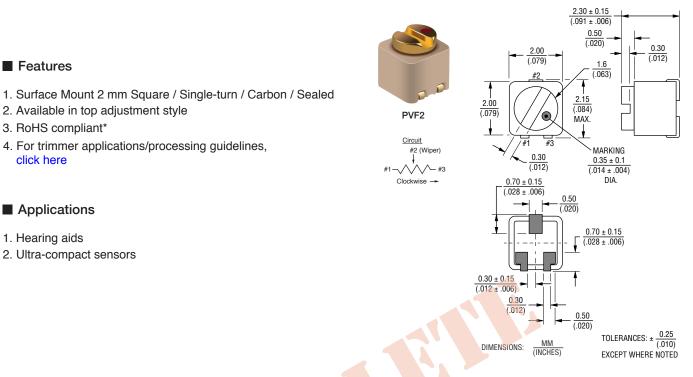
BOURN

®

# **Trimmer Potentiometers**

# SMD Sealed Type Single-Turn PVF2 Series



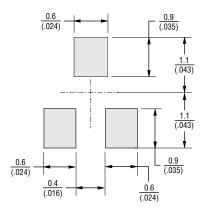
## **Top Adjustment**

Part Number	Power Rating (W)	Number of Turns (Effective Rotation Angle)	Total Resistance Value	TCR (ppm/°C)
PVF2A204A1AR03	0.001 (50 °C)	1	200k ohms ±10 %	±500

Operating Temperature Range: -25 to +60 °C

Soldering Method: Forced Hot Air, Convection, IR, Vapor Phase (In-Line)

### Standard Land Pattern



 $\begin{array}{l} \text{DIMENSIONS: } \frac{\text{MM}}{(\text{INCHES})} \\ \text{TOLERANCES: } \pm \frac{0.1}{(.004)} \\ \text{EXCEPT WHERE NOTED} \end{array}$ 



\*RoHS Directive 2002/95/EC Jan. 27, 2003 including annex and RoHS Recast 2011/65/EU June 8, 2011. Specifications are subject to change without notice.

The device characteristics and parameters in this data sheet can and do vary in different applications and actual device performance may vary over time. Users should verify actual device performance in their specific applications.

#### Characteristics

Temperature Cycle	ΔTR	: ±5%
Humidity	ΔTR	: +15%/-2%
Vibration (20G)	ΔTR	: ±5%
Shock (100G)	ΔTR	: ±5%
Temperature Load Life	ΔTR	: +2%/-10%
Low Temperature Exposure	ΔTR	: ±3%
Rotational Life	ΔTR	: ±10% (100 cycles)

ΔTR: Total Resistance Change

Part Numbering									
Product ID — PV = Trimming Potention Series — F2 = 2 mm Square, Single Adjustment Direction/Lead T A = Top / In-line	e-turn Adjustment	A 20	04 A <sup>-</sup>		03				
Total Resistance Expressed by three figure The first and second figur significant digits; the third the number of zeros that	res are d figure expresses								
Resistance (Ohms)	Resistance Code								
200,000	204								
Individual Specification — A1A = Rotor preset at clo Packaging —	ockwise position			I					

R03 = Tape and Reel (1500 pcs. per 7 " reel)



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